

Bill of Materials

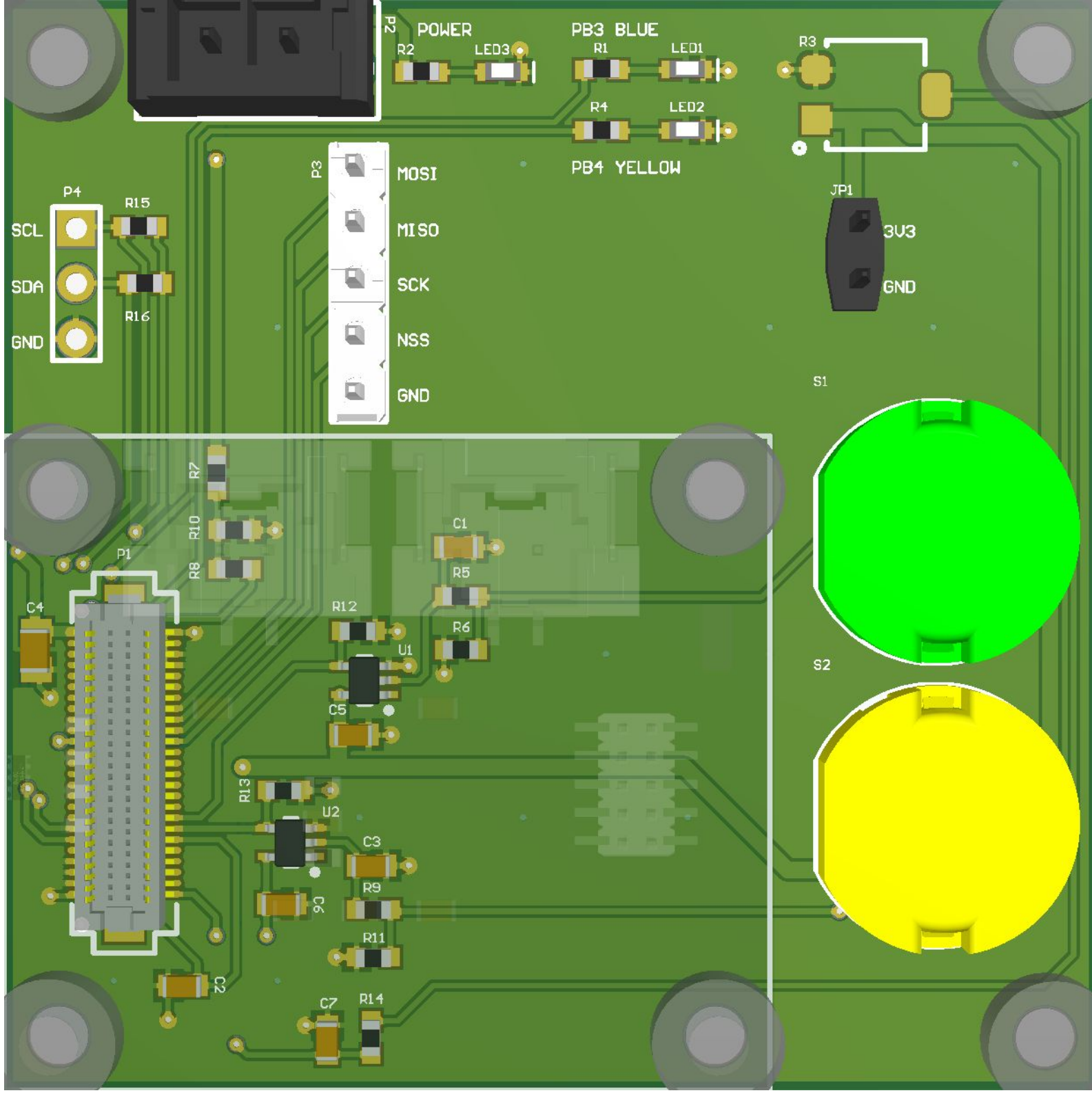
Project:	HW_Tutorial.PrjPcb
Revision:	2.0
Project Lead:	Mena Labib
Generated On:	2019-09-14 2:19 PM
Production Quantity:	1
Currency	CAD
Total Parts Count:	35

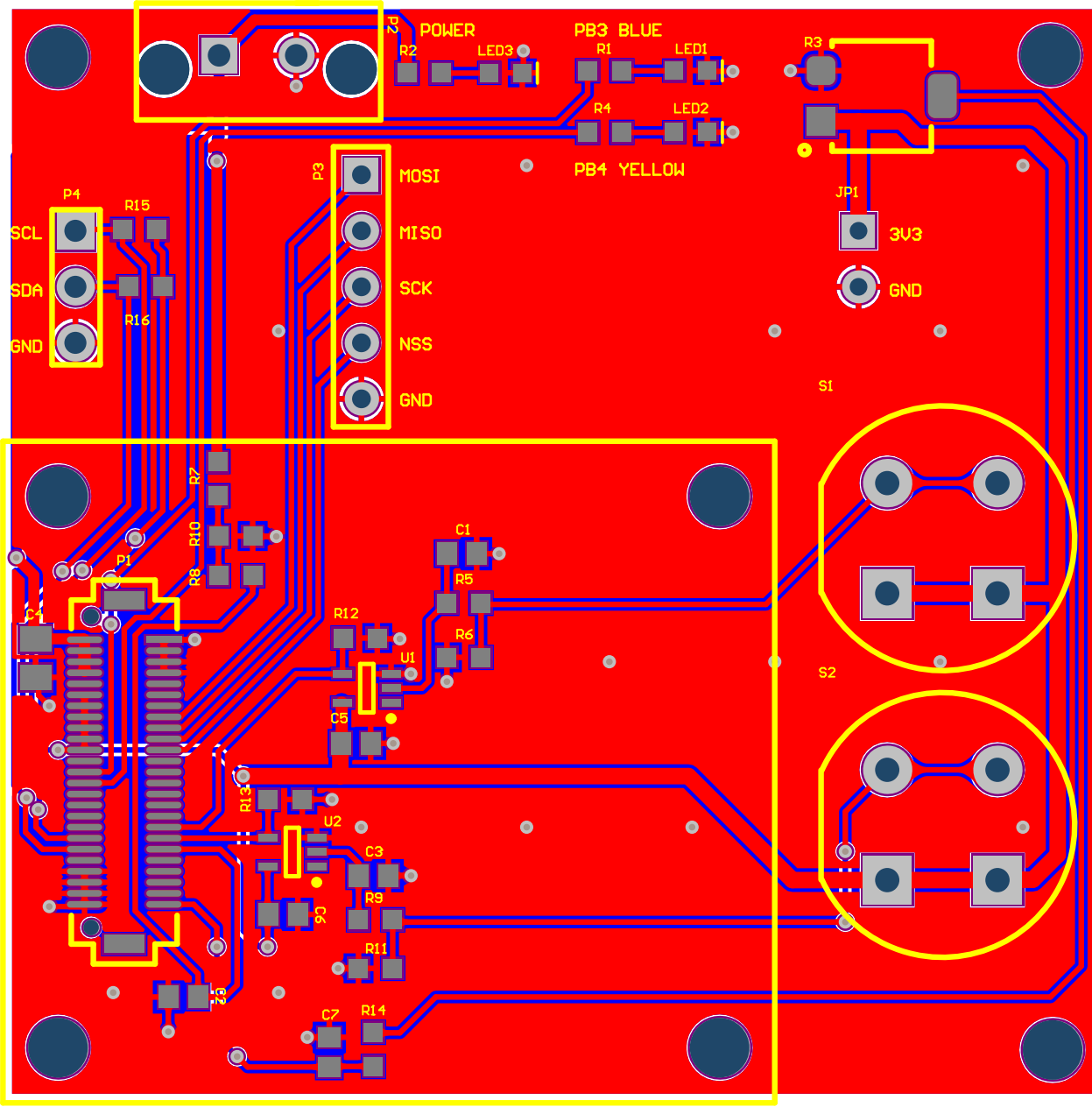
MIDNIGHT

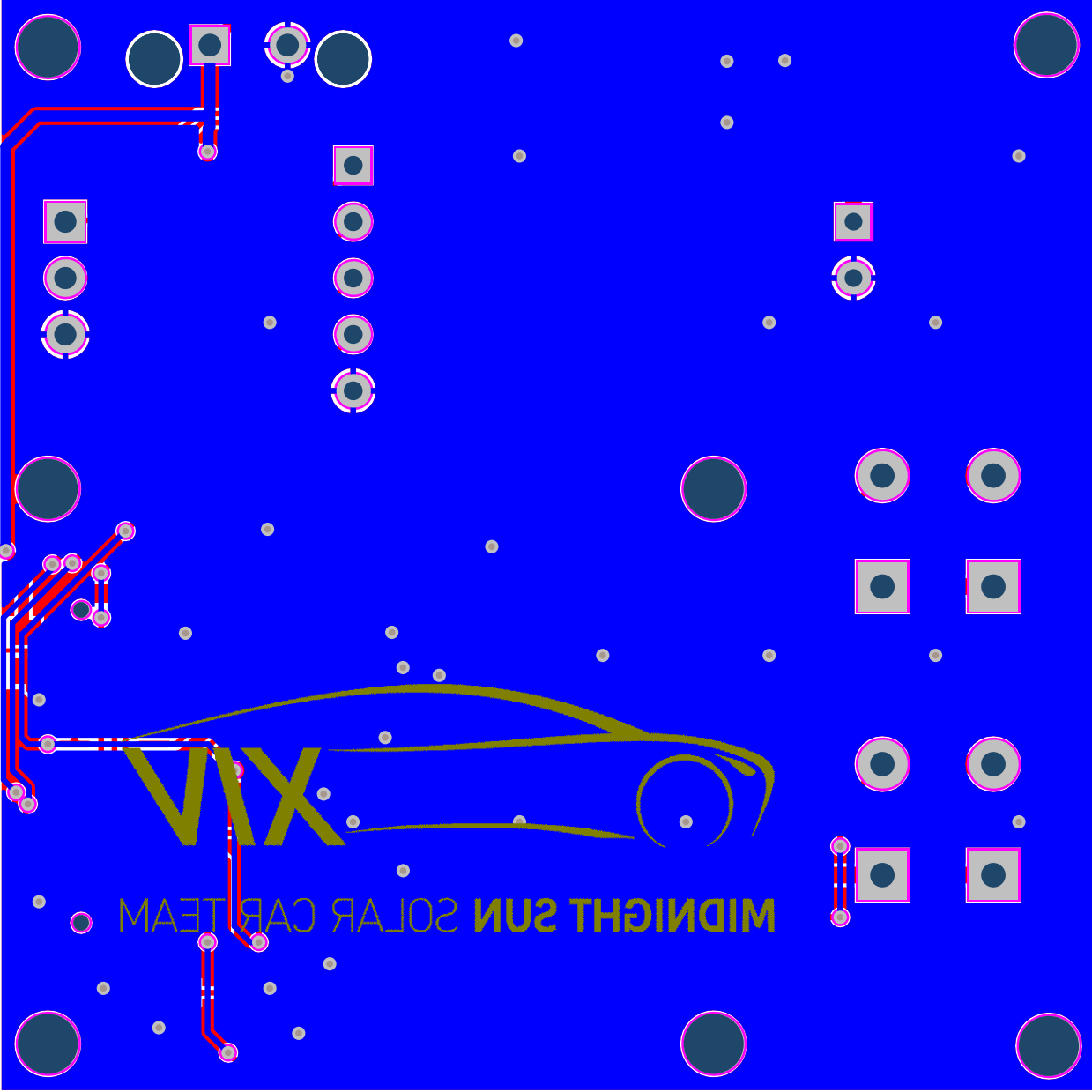


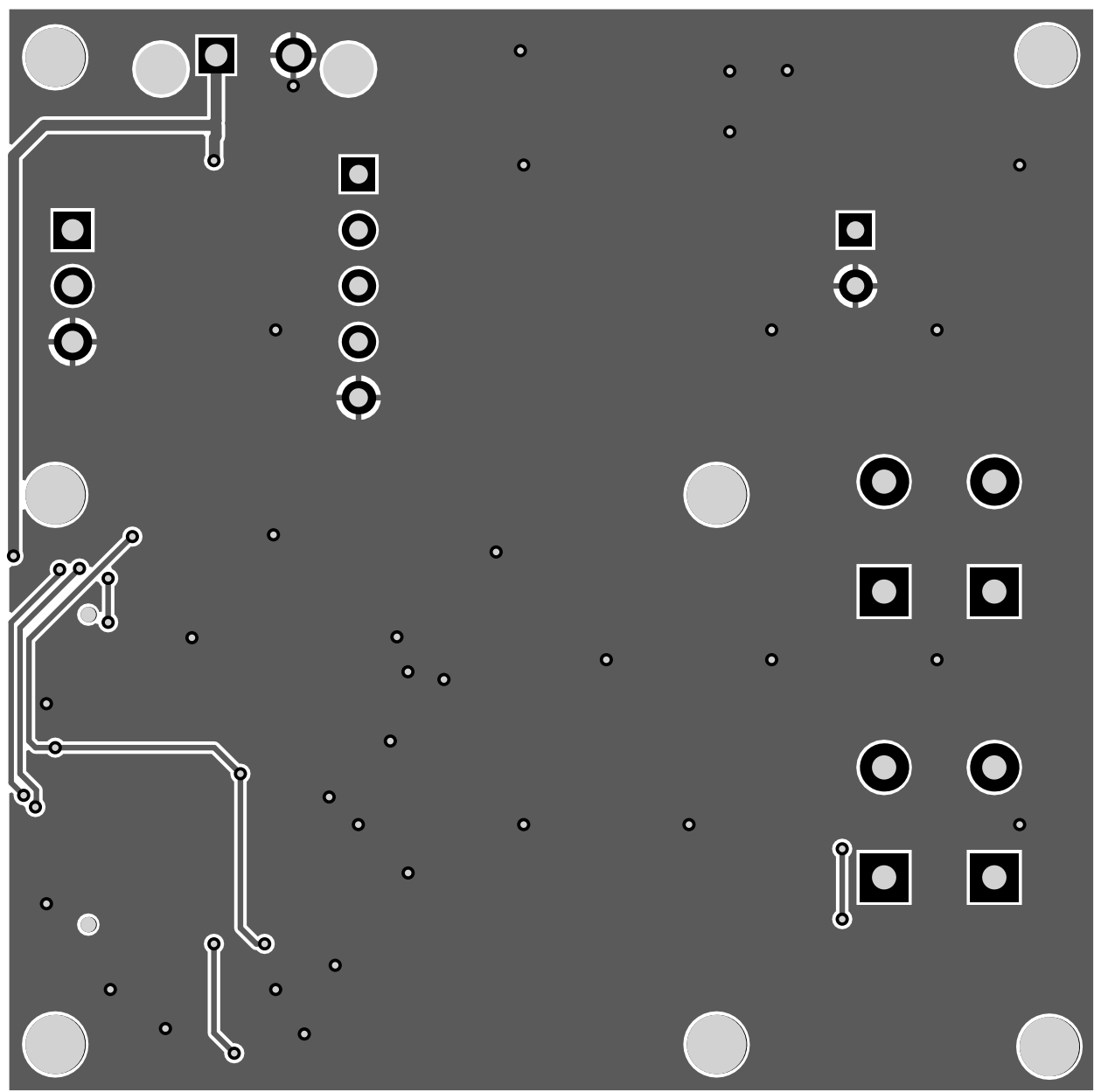
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LibRef	Designator	Manufacturer 1	Manufacturer Part Number 1	Supplier 1	Supplier Part Number 1	Supplier Unit Price
CAP CER 4.7UF 25V 10% X5R 0603	C1, C3, C7	Murata	GRM188R61E475KE11D	Digi-Key	490-7203-1-ND	0.49096
CAP CER 0.1UF 50V 10% X7R 0603	C2, C5, C6	Kyocera AVX	06035C104KAT2A	Digi-Key	478-5052-1-ND	0.19904
CAP CER 10uF 25V 10% X5R 0805	C4	Murata	GRM21BR61E106KA73L	Digi-Key	490-5523-1-ND	0.57058
CONN 2POS JUMPER 0.1"	JP1	Omron	XG8T-0231	Digi-Key	XG8T-0231-ND	0.25212
LED BLUE CLEAR 2.8V 0603	LED1	Vishay Lite-On	LTST-C193TBKT-5A	Digi-Key	160-1827-1-ND	0.59712
LED YELLOW CLEAR 2.1V 0603	LED2	Würth Electronics	150060YS75000	Digi-Key	732-4981-1-ND	0.18577
LED GREEN CLEAR 2V 0603	LED3	Würth Electronics	150060VS75000	Digi-Key	732-4980-1-ND	0.18577
CONN 50POS Bergstak Plug 0.02"	P1	Amphenol FCI	10132797-055100LF	Digi-Key	609-5226-1-ND	1.86
CONN 2POS ULTRA-FIT 0.138"	P2	Molex	1722861302	Digi-Key	WM11673-ND	1.94
CONN 5POS HEADR MALE 0.1in	P3	Molex	0022284050	Digi-Key	WM50014-05-ND	0.31846
CONN 3POS HEADR MALE 0.1"	P4	Würth Electronics	61300311121	Digi-Key	732-5316-ND	0.1725
RES 100 OHM 1% 1/10W 0603	R1, R4	Yageo	RC0603FR-07100RL	Digi-Key	311-100HRC-ND	0.13269
RES 10K OHM 1% 1/10W 0603	R2, R7, R8, R15, R16	Yageo Phycomp	RC0603FR-0710KL	Digi-Key	311-10.0KHRCT-ND	0.13269
POT 20k OHM 20% 1/4W	R3	TT BI	23BR20KLFTR	Digi-Key	987-1016-1-ND	1.69
RES 1K OHM 5% 1/10W 0603	R5, R6, R9, R11, R12, R13, R14	Yageo	RC0603JR-071KL	Digi-Key	311-1.0KGRC-ND	0.13269
RES 3.3K OHM 1% 1/4W 0603	R10	Panasonic	ERJ-PA3F3301V	Digi-Key	P3.3KBYCT-ND	0.21231
SW SPST-NO 0.1A 32V D6 Series Green	S1	ITT C&K	D6R50F1LFS	Digi-Key	401-1976-ND	1.59
SW SPST-NO 0.1A 32V D6 Series Yellow	S2	ITT C&K	D6R30F1LFS	Digi-Key	401-1974-ND	1.59
IC INVERTER SCHMITT 1CH SC70-5	U1, U2	Texas Instruments	SN74LVC1G14QDCKRQ1	Digi-Key	296-47215-1-ND	0.47769









Electrical Rules Check Report

Class	Document	Message
Warning	hw_tutorial.SchDoc	Extra Pin R3-2 (Inferred) in Alternate 1 of part R3
Warning	hw_tutorial.SchDoc	Extra Pin R3-2 in Normal of part R3
Warning	hw_tutorial.SchDoc	Extra Pin R3-3 (Inferred) in Alternate 1 of part R3
Warning	hw_tutorial.SchDoc	Extra Pin R3-3 in Normal of part R3

Design Rules Verification Report

Filename : C:\Users\Aashmika Mali\Documents\First Year\Midnight Sun\hardware\MSXII_

Warnings 0
Rule Violations 111

Warnings	
Total	0

Rule Violations	
Clearance Constraint (Gap=0.152mm) (All),(All)	0
Short-Circuit Constraint (Allowed=No) (All),(All)	0
Un-Routed Net Constraint ((All))	0
Modified Polygon (Allow modified: No), (Allow shelved: No)	0
Width Constraint (Min=0.152mm) (Max=2.54mm) (Preferred=0.254mm) (All)	0
Power Plane Connect Rule(Relief Connect)(Expansion=0.508mm) (Conductor Width=0.254mm) (Air Gap=0.254mm)	0
Minimum Annular Ring (Minimum=0.152mm) (All)	49
Hole Size Constraint (Min=0.3mm) (Max=6.3mm) (All)	0
Hole To Hole Clearance (Gap=0.254mm) (All),(All)	0
Minimum Solder Mask Sliver (Gap=0.3mm) (All),(All)	35
Silk To Solder Mask (Clearance=0.178mm) (IsPad),(All)	8
Silk to Silk (Clearance=0.254mm) (All),(All)	1
Net Antennae (Tolerance=0mm) (All)	0
Board Clearance Constraint (Gap=0mm) (All)	18
Height Constraint (Min=0mm) (Max=25.4mm) (Preferred=12.7mm) (All)	0
Total	111

[illegible]

Minimum Annular Ring: (0.15mm < 0.152mm) Via (9.7mm, 7.075mm) from Top Layer to Bottom Layer (Annular Ring=0.15mm) On (Top Layer)

Minimum Solder Mask Sliver (Gap=0.3mm) (All),(All)

Minimum Solder Mask Sliver Constraint: (0.298mm < 0.3mm) Between Pad C1-1(20.133mm,24.9mm) on Top Layer And Pad C1-2(21.483mm,24.9mm)
Minimum Solder Mask Sliver Constraint: (0.089mm < 0.3mm) Between Pad C1-2(21.483mm,24.9mm) on Top Layer And Via (22.5mm,24.9mm) from Top
Minimum Solder Mask Sliver Constraint: (0.298mm < 0.3mm) Between Pad C2-1(8.85mm,4.8mm) on Top Layer And Pad C2-2(7.5mm,4.8mm) on Top
Minimum Solder Mask Sliver Constraint: (0.298mm < 0.3mm) Between Pad C3-1(16.125mm,10.3mm) on Top Layer And Pad C3-2(17.475mm,10.3mm)
Minimum Solder Mask Sliver Constraint: (0.105mm < 0.3mm) Between Pad C3-2(17.475mm,10.3mm) on Top Layer And Via (18.508mm,10.3mm) from
Minimum Solder Mask Sliver Constraint: (0.217mm < 0.3mm) Between Pad C4-2(1.476mm,19.295mm) on Top Layer And Via (2.1mm,18mm) from Top
Minimum Solder Mask Sliver Constraint: (0.298mm < 0.3mm) Between Pad C5-1(15.325mm,16.3mm) on Top Layer And Pad C5-2(16.675mm,16.3mm)
Minimum Solder Mask Sliver Constraint: (0.097mm < 0.3mm) Between Pad C5-2(16.675mm,16.3mm) on Top Layer And Via (17.7mm,16.3mm) from Top
Minimum Solder Mask Sliver Constraint: (0.298mm < 0.3mm) Between Pad C6-1(12.025mm,8.546mm) on Top Layer And Pad C6-2(13.375mm,8.546mm)
Minimum Solder Mask Sliver Constraint: (0.298mm < 0.3mm) Between Pad C7-1(14.8mm,1.625mm) on Top Layer And Pad C7-2(14.8mm,2.975mm) or
Minimum Solder Mask Sliver Constraint: (0.022mm < 0.3mm) Between Pad C7-2(14.8mm,2.975mm) on Top Layer And Via (13.8mm,2.975mm) from Top
Minimum Solder Mask Sliver Constraint: (0.258mm < 0.3mm) Between Pad LED1-2(31.939mm,46.805mm) on Top Layer And Via (33.1mm,46.77mm)
Minimum Solder Mask Sliver Constraint: (0.258mm < 0.3mm) Between Pad LED2-2(31.939mm,44.012mm) on Top Layer And Via (33.1mm,44.012mm)
Minimum Solder Mask Sliver Constraint: (0.097mm < 0.3mm) Between Pad LED3-2(23.55mm,46.7mm) on Top Layer And Via (23.6mm,47.7mm) from
Minimum Solder Mask Sliver Constraint: (0.105mm < 0.3mm) Between Pad P1-(4mm,22.05mm) on Multi-Layer And Pad P1-(5.5mm,22.8mm) on Top
Minimum Solder Mask Sliver Constraint: (0.112mm < 0.3mm) Between Pad P1-(4mm,22.05mm) on Multi-Layer And Via (4.9mm,21.7mm) from Top Layer
Minimum Solder Mask Sliver Constraint: (0.105mm < 0.3mm) Between Pad P1-(4mm,7.95mm) on Multi-Layer And Pad P1-(5.5mm,7.2mm) on Top Layer
Minimum Solder Mask Sliver Constraint: (0.197mm < 0.3mm) Between Pad P1-(5.5mm,22.8mm) on Top Layer And Via (4.9mm,21.7mm) from Top Layer
Minimum Solder Mask Sliver Constraint: (0.097mm < 0.3mm) Between Pad P1-1(7.3mm,21mm) on Top Layer And Via (8.7mm,21mm) from Top Layer to
Minimum Solder Mask Sliver Constraint: (0.248mm < 0.3mm) Between Pad P1-2(7.3mm,20.5mm) on Top Layer And Via (8.7mm,21mm) from Top Layer
Minimum Solder Mask Sliver Constraint: (0.09mm < 0.3mm) Between Pad P1-39(3.7mm,15.5mm) on Top Layer And Via (2.5mm,16mm) from Top Layer
Minimum Solder Mask Sliver Constraint: (0.09mm < 0.3mm) Between Pad P1-41(3.7mm,16.5mm) on Top Layer And Via (2.5mm,16mm) from Top Layer
Minimum Solder Mask Sliver Constraint: (0.297mm < 0.3mm) Between Pad P1-44(3.7mm,18mm) on Top Layer And Via (2.1mm,18mm) from Top Layer
Minimum Solder Mask Sliver Constraint: (0.237mm < 0.3mm) Between Pad P1-50(3.7mm,21mm) on Top Layer And Via (4.9mm,21.7mm) from Top Layer
Minimum Solder Mask Sliver Constraint: (0.092mm < 0.3mm) Between Pad P2-2(13.3mm,47.495mm) on Multi-Layer And Via (13.3mm,46.1mm) from Top
Minimum Solder Mask Sliver Constraint: (0.147mm < 0.3mm) Between Pad R10-2(11.325mm,25.7mm) on Top Layer And Via (12.4mm,25.68mm) from
Minimum Solder Mask Sliver Constraint: (0.097mm < 0.3mm) Between Pad R12-1(16.975mm,21.075mm) on Top Layer And Via (18mm,21.037mm) from
Minimum Solder Mask Sliver Constraint: (0.239mm < 0.3mm) Between Pad R3-3(37.1mm,46.8mm) on Top Layer And Via (35.708mm,46.802mm) from
Minimum Solder Mask Sliver Constraint: (0.172mm < 0.3mm) Between Pad R6-1(20.133mm,20.2mm) on Top Layer And Via (20.133mm,19.1mm) from
Minimum Solder Mask Sliver Constraint: (0.097mm < 0.3mm) Between Pad U1-1(17.6mm,18.15mm) on Top Layer And Pad U1-2(17.6mm,18.8mm) or
Minimum Solder Mask Sliver Constraint: (0.097mm < 0.3mm) Between Pad U1-2(17.6mm,18.8mm) on Top Layer And Pad U1-3(17.6mm,19.45mm) or
Minimum Solder Mask Sliver Constraint: (0.126mm < 0.3mm) Between Pad U1-2(17.6mm,18.8mm) on Top Layer And Via (18.5mm,19.45mm) from Top
Minimum Solder Mask Sliver Constraint: (0.097mm < 0.3mm) Between Pad U2-1(14.225mm,10.725mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.097mm < 0.3mm) Between Pad U2-2(14.225mm,11.375mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.098mm < 0.3mm) Between Via (2.7mm,24.1mm) from Top Layer to Bottom Layer And Via (3.6mm,24.15mm)

Silk To Solder Mask (Clearance=0.178mm) (IsPad),(All)

Silk To Solder Mask Clearance Constraint: (0.082mm < 0.178mm) Between Pad P4-1(3.286mm,39.54mm) on Multi-Layer And Track
Silk To Solder Mask Clearance Constraint: (Collision < 0.178mm) Between Pad P4-1(3.286mm,39.54mm) on Multi-Layer And Track
Silk To Solder Mask Clearance Constraint: (0.144mm < 0.178mm) Between Pad P4-1(3.286mm,39.54mm) on Multi-Layer And Track
Silk To Solder Mask Clearance Constraint: (0.088mm < 0.178mm) Between Pad P4-2(3.286mm,37mm) on Multi-Layer And Track
Silk To Solder Mask Clearance Constraint: (0.168mm < 0.178mm) Between Pad P4-2(3.286mm,37mm) on Multi-Layer And Track
Silk To Solder Mask Clearance Constraint: (0.088mm < 0.178mm) Between Pad P4-3(3.286mm,34.46mm) on Multi-Layer And Track
Silk To Solder Mask Clearance Constraint: (0.169mm < 0.178mm) Between Pad P4-3(3.286mm,34.46mm) on Multi-Layer And Track
Silk To Solder Mask Clearance Constraint: (0.168mm < 0.178mm) Between Pad P4-3(3.286mm,34.46mm) on Multi-Layer And Track

Silk to Silk (Clearance=0.254mm) (All),(All)

Silk To Silk Clearance Constraint: (0.183mm < 0.254mm) Between Text "P2" (17.477mm,49.2mm) on Top Overlay And Track

Board Clearance Constraint (Gap=0mm) (All)
Board Outline Clearance(Outline Edge): (0.3mm < 0.406mm) Between Board Edge And Text "GND" (0.4mm,34.06mm) on Top Overlay
Board Outline Clearance(Outline Edge): (0.3mm < 0.406mm) Between Board Edge And Text "SCL" (0.4mm,39.2mm) on Top Overlay
Board Outline Clearance(Outline Edge): (0.3mm < 0.406mm) Between Board Edge And Text "SDA" (0.4mm,36.6mm) on Top Overlay
Board Outline Clearance(Outline Edge): (0.375mm < 0.406mm) Between Board Edge And Track (0.5mm,14.4mm)(0.5mm,21.7mm) on Bottom Layer
Board Outline Clearance(Outline Edge): (0.375mm < 0.406mm) Between Board Edge And Track (0.5mm,14.4mm)(1.068mm,13.832mm) on Bottom Layer
Board Outline Clearance(Outline Edge): (0.375mm < 0.406mm) Between Board Edge And Track (0.5mm,21.7mm)(2.633mm,23.833mm) on Bottom Layer
Board Outline Clearance(Outline Edge): (0.356mm < 0.406mm) Between Board Edge And Track (0.606mm,24.719mm)(0.606mm,42.918mm) on Bottom Layer
Board Outline Clearance(Outline Edge): (0.356mm < 0.406mm) Between Board Edge And Track (0.606mm,24.719mm)(1.4mm,23.926mm) on Top Overlay
Board Outline Clearance(Outline Edge): (0.356mm < 0.406mm) Between Board Edge And Track (0.606mm,42.918mm)(1.993mm,44.305mm) on Bottom Layer
Board Outline Clearance(Outline Edge): (Collision < 0.406mm) Between Board Edge And Track (0mm,0mm)(0mm,30mm) on Top Overlay
Board Outline Clearance(Outline Edge): (Collision < 0.406mm) Between Board Edge And Track (0mm,0mm)(35mm,0mm) on Top Overlay
Board Outline Clearance(Outline Edge): (Collision < 0.406mm) Between Board Edge And Track (0mm,30mm)(35mm,30mm) on Top Overlay
Board Outline Clearance(Outline Edge): (Collision < 0.406mm) Between Board Edge And Track (13.3mm,49.865mm)(17.13mm,49.865mm) on Top Overlay
Board Outline Clearance(Outline Edge): (Collision < 0.406mm) Between Board Edge And Track (17.13mm,44.565mm)(17.13mm,49.865mm) on Top Overlay
Board Outline Clearance(Outline Edge): (Collision < 0.406mm) Between Board Edge And Track (35mm,0mm)(35mm,30mm) on Top Overlay
Board Outline Clearance(Outline Edge): (Collision < 0.406mm) Between Board Edge And Track (6.055mm,44.565mm)(6.055mm,49.865mm) on Top Overlay
Board Outline Clearance(Outline Edge): (Collision < 0.406mm) Between Board Edge And Track (6.055mm,49.865mm)(14.3mm,49.865mm) on Top Overlay
Board Outline Clearance(Outline Edge): (0.306mm < 0.406mm) Between Board Edge And Via (0.606mm,24.719mm) from Top Layer to Bottom Layer